

Form PTO-1595 (Rev. 07/05)
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U.S. DEPARTMENT OF COMMERCE
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RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)
Cheng C. Wang

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
Name: Flex Logix Technologies, Inc.
Internal Address: _____
Street Address: 2465 Latham Street, Suite 100
City: Mountain View
State: _____
Country: California Zip: 94040

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance/Execution Date(s):
Execution Date(s) October 29, 2019

Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other _____

4. Application or patent number(s): This document is being filed together with a new application.

A. Patent Application No.(s)
16/545,345

Additional numbers attached? Yes No

B. Patent No.(s)

5. Name and address to whom correspondence concerning document should be mailed:
Name: Neil A. Steinberg
Internal Address: _____
Street Address: 5335 Wisconsin Ave. NW Suite 440
City: Washington
State: D.C. Zip: 20015
Phone Number: 202-746-8133
Fax Number: 202-730-1249
Email Address: neils@swpatentlaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 50.00

Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number 50-0763
Authorized User Name Neil A. Steinberg

9. Signature: Neil A. Steinberg Signature October 30, 2019 Date

Neil A. Steinberg
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 3

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

CH \$50.00 16545345

ASSIGNMENT
(Attorney Ref. 401.015-US)

Inventor: **Cheng C. Wang**

Application No.: **16/545,345**

Title: **Multiplier-Accumulator Circuit, Logic
Tile Architecture for Multiply-Accumulate,
and IC including Logic Tile Array**

Filing Date: **August 20, 2019**

I, the undersigned, in consideration of good and valuable considerations in hand paid, the receipt and sufficiency whereof are hereby acknowledged, hereby assign to

Flex Logix Technologies, Inc.

(2465 Latham Street, Suite 100, Mountain View, California), and its successors and assigns, the entire right, title and interest in: (i) the above-referenced patent application, and (ii) the inventions and/or improvements disclosed and/or claimed in the above-referenced patent application, and (iii) any and all other patent applications of the United States and foreign countries which claim priority to the above-referenced application and/or which may be filed, either solely or jointly with others, on the inventions and/or improvements disclosed and/or claimed in the above-referenced patent application, and (iv) any and all patents of the United States and foreign countries which may be obtained on any of the aforementioned applications, and (v) any reissue, reexamination or extension of such aforementioned patents, and further assign to said assignee the priority right provided by the International Convention.

I, the undersigned, hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patents to said assignee, its successors and assigns, in accordance with the terms of this Assignment.

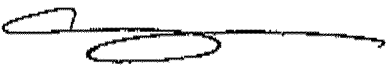
I, the undersigned, hereby authorize and request the Assignee to insert in this instrument the filing date and application number of the application when ascertained.

I, the undersigned, warrant that there are no outstanding prior assignments, licenses, or other encumbrances on the interests herein assigned, other than those assignments, licenses, or other encumbrances already assigned to **Flex Logix Technologies, Inc.**

I, the undersigned, for said considerations hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all

divisional, continuation and substitute applications for said inventions and/or improvements, and any necessary oath, affidavit or declaration relating thereto, and any application for the reissue, reexamination or extension of any patents that may be granted on said application and any and all applications and other documents for patents in foreign countries on said inventions and/or improvements, that said assignee, its successors or assigns may deem necessary or expedient, and for the said considerations the undersigned authorize said assignee to apply for patents for said inventions and/or improvements in its own name in such countries where such procedure is proper and further agree, upon the request of said assignee, its successors and assigns, to cooperate to the best of the ability of the undersigned with said assignee, its successors and assigns, in any proceedings or transactions involving such applications or patents, including the preparation and execution of preliminary statements, giving and producing evidence, and performing any and all other acts necessary to obtain said patents, both United States and foreign, and vest all rights therein hereby conveyed in the assignee, its successors and assigns, whereby all said patents will be held and enjoyed by the said assignee, its successors and assigns, to the full end of the term for which said patents will be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment had not been made.

Date: 10/29/19



Cheng C. Wang